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# On the Performances of $Cu_xO-TiO_2$ (x = 1, 2) Nanomaterials As Innovative Anodes for Thin Film Lithium Batteries

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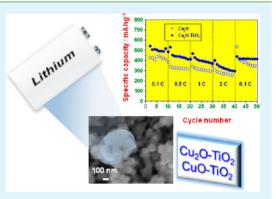
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Supporting Information

**ABSTRACT:**  $Cu_xO-TiO_2$  (x = 1, 2) nanomaterials are synthesized on polycrystalline Ti substrates by a convenient chemical vapor deposition (CVD) approach, based on the initial growth of a  $Cu_xO$  matrix (at 400 and 550 °C for x = 1 and 2, respectively) and the subsequent overdispersion of TiO<sub>2</sub> at 400 °C. All CVD processes are carried out in an oxygen atmosphere saturated with water vapor. The obtained systems are investigated by means of glancing incidence X-ray diffraction (GIXRD), X-ray photoelectron spectroscopy (XPS), secondary ion mass spectrometry (SIMS), field emission-scanning electron microscopy (FE-SEM), atomic force microscopy (AFM), and electrochemical experiments. Galvanostatic charge/discharge measurements indicate that  $Cu_2O$ -TiO<sub>2</sub> nanomaterials exhibit very attractive high-rate capabilities (~400 mA h g<sup>-1</sup> at 1 C; ~325 mA h g<sup>-1</sup> at 2 C) and good stability after 50 operating cycles, with a retention of 80% of the initial



capacity. This phenomenon is mainly due to the presence of  $TiO_2$  acting as a buffer material, i.e., minimizing volume changes occurring in the electrochemical conversion. In a different way,  $CuO-TiO_2$  systems exhibit worse electrochemical performances as a consequence of their porous morphology and higher thickness. In both cases, the obtained values are among the best ever reported for  $Cu_xO$ -based systems, candidating the present nanomaterials as extremely promising anodes for eventual applications in thin film lithium batteries.

KEYWORDS: chemical vapor deposition, copper oxides, titanium dioxide, energy storage, thin film lithium batteries

# INTRODUCTION

In the search for high storage capacity and cost-effective anode materials for innovative thin film lithium batteries, transition metal oxides ( $M_xO_y$ , with M = Fe, Co, Ni, and Cu) have been widely investigated since they were first proposed by Tarascon et al.<sup>1</sup> In fact, these materials have the ability to reversibly store a high Li amount through a heterogeneous conversion reaction<sup>2–5</sup>

$$2y\text{Li} + M_xO_y \rightleftharpoons y\text{Li}_2O + xM \tag{1}$$

Nevertheless, the application of such oxides is often hindered by their modest electronic conductivity and large volume changes occurring during charge/discharge cycles. In particular, the latter effect might result in  $M_xO_y$  pulverization,<sup>6</sup> and subsequent polarization/insulation of the electrode. This issue still needs to be adequately addressed by a suitable choice of active materials and the development of versatile synthetic protocols enabling to tailor the system structural and morphological organization. As a consequence, fundamental research in this field is still necessary and highly demanded.

Among transition metal oxides, Cu<sub>2</sub>O and CuO are undoubtedly an attractive choice,<sup>2,5,6</sup> since they are abundant, environmentally benign and inexpensive in comparison to other investigated systems.<sup>7,8</sup> In spite of these advantages, a key challenge for  $Cu_xO(x = 1, 2)$  practical use in thin film lithium batteries is the improvement of their high-rate capacity and cycling performances, which are both still far from meeting technological requirements. In this regard, various research efforts have been devoted to the preparation of nanostructured Cu<sub>x</sub>O materials with different morphologies (e.g., nanoparticles, nanowires, nanosheets, hollow nanostructures, ...),<sup>2-4,6,9-17</sup> with particular attention to nanocomposites with tailored spatial organization.<sup>5,18–28</sup> Despite improved electrochemical performances having been reported for these systems, thanks to the large active surface area and the decreased diffusion pathway for both electrons and lithium ions,<sup>6,7,29</sup> the charge transfer between copper oxides and current collector is still

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limited, especially at high cycling rates.<sup>5</sup> In an attempt to solve this problem, powdered Cu.O were blended with conductive reagents/polymer binders<sup>3,6</sup> to coat the metal collector. Nevertheless, disadvantages related to the poor contact of the latter with the oxide phase, as well as to the formation of additional inactive interfaces between CuxO and binders, have still to be fully overcome.<sup>4,5</sup> To this aim, the preparation of supported and nanostructured copper oxides is a valuable option for use in thin film lithium batteries, since the intimate contact with the current collector facilitates electron transfer processes, avoiding the use of any ancillary additive. In this context, a careful control of grain size and film thickness must be properly pursued in order to avoid detrimental alterations of the contact area between Cu<sub>x</sub>O particles and the electrolyte,<sup>5</sup> whose diffusion through the film restrains the electrochemical reactivity.

Herein, we present an unprecedented strategy for the preparation of Ti-supported copper oxide-based electrodes for thin film lithium batteries. The proposed strategy consists in the initial chemical vapor deposition (CVD) of  $Cu_xO$ nanomaterials starting from Cu(hfa)<sub>2</sub>·TMEDA (hfa = 1,1,1,5,5,5-hexafluoro-2,4-pentanedionate; TMEDA = N,N,N',N' - tetramethylethylenediamine). Such a route led to the selective obtainment of Cu<sub>2</sub>O or CuO nanomaterials by varying the growth temperature (400, 550 °C) and the operating pressure (3, 10 mbar).<sup>30-33</sup> Beside enabling us to avoid the use of binders and/or ancillary materials,<sup>3</sup> <sup>8</sup> this approach resulted in an optimal adhesion between Cu.O and the used titanium substrate. In a subsequent processing step, the deposition of controlled TiO2 amounts was performed adopting  $Ti(O^{-i}Pr)_2(dpm)_2$  (O<sup>-i</sup>Pr = isopropoxy; dpm = 2,2,6,6-tetramethyl-3,5-heptanedionate) as precursor. The overdispersion of TiO<sub>2</sub> on copper oxides, reported for the first time in the present work, was aimed at improving the anode electrochemical efficiency.

Notably, the vapor phase strategy proposed herein enabled a simultaneous tailoring of the system phase composition and nano-organization, with an intimate contact between  $Cu_xO$  and  $TiO_2$ . These features synergistically contributed to the attractive electrochemical behavior observed for the assembled electrodes, in terms of both specific capacities and cycling performances.

To date, only a few works on Cu/TiO<sub>2</sub> nanocomposites for such applications are available in the literature, dealing with the use of copper-containing particles as intermixed current collectors to improve TiO<sub>2</sub> electrochemical performance.<sup>7,29,30</sup> The proposed synthesis involved the slurry casting of powdered materials onto the current collectors after mixing with conductive additives, whose use can be conveniently avoided by the present synthetic strategy.<sup>7,29</sup> Though representing a fundamental study, the results obtained in this work can provide a valuable guidance in view of further optimization of standard batteries.

#### EXPERIMENTAL SECTION

**Synthesis.** Copper oxide nanostructures were grown by a custombuilt cold-wall CVD apparatus consisting of a tubular quartz chamber, a resistively heated susceptor, and an external reservoir for precursor vaporization,<sup>34</sup> adopting Cu(hfa)<sub>2</sub>. TMEDA as molecular source.<sup>35</sup> On the basis of our recent results,<sup>31,32</sup> the synthesis of pure Cu<sub>2</sub>O and CuO nanostructures was performed at temperatures of 400 and 550 °C (deposition time = 2 h; precursor vaporization temperature = 70 °C). Vapor transport toward the deposition zone was performed through heated gas lines (120 °C) by an O<sub>2</sub> flow (purity = 6.0; flow rates = 20 and 100 sccm for Cu<sub>2</sub>O and CuO, respectively). In addition, an auxiliary oxygen flow (20 and 100 sccm for the two cases) was introduced separately into the reaction chamber after passing through a water reservoir (50 °C). Total pressures were set at 3.0 and 10.0 mbar for Cu<sub>2</sub>O and CuO, respectively, with corresponding estimated H<sub>2</sub>O partial pressures of ~0.3 and 1.5 mbar.<sup>34</sup> Depositions were performed on Ti substrates (99.7%, Aldrich; thickness = 0.25 mm, size =  $8 \times 8 \text{ mm}^2$ ), previously subjected to ultrasonic degreasing in dichloromethane, rinsing in isopropanol, and final drying in air.

Subsequent TiO<sub>2</sub> dispersion was performed starting from Ti-(O-'Pr)<sub>2</sub>(dpm)<sub>2</sub> (99.99%, Aldrich; vaporization temperature = 80 °C) adopting the same CVD equipment, at total pressure of 10.0 mbar and substrate temperature of 400 °C [deposition time = 20 min, 40 and 80 sccm flow rates for the precursor mass-transport (O<sub>2</sub>) and the auxiliary inlet (O<sub>2</sub> + H<sub>2</sub>O), respectively]. The use of higher temperatures was discarded in order to prevent undesired modifications of Cu<sub>2</sub>O and CuO matrices. All the other parameters were set as for the Cu<sub>x</sub>O deposition. The obtained Cu<sub>x</sub>O-TiO<sub>2</sub> composite samples were cooled down at room temperature before contacting the external atmosphere and subsequently characterized without any ex situ treatment.

**Characterization.** GIXRD patterns were collected at a constant incidence angle of 1° by a Bruker D8 Advance diffractometer equipped with a Göbel mirror, using a Cu K $\alpha$  X-ray source powered at 40 kV and 40 mA. Scherrer equation was used to estimate the mean crystallite sizes.

XPS analyses were carried out by a Perkin-Elmer  $\Phi$ 5600ci spectrometer at pressures lower than  $10^{-8}$  mbar, using a nonmonochromatized Mg K $\alpha$  source ( $h\nu = 1253.6$  eV). After a Shirleytype background subtraction, raw spectra were fitted by a least-squares deconvolution, adopting Gaussian–Lorentzian peak shapes. The reported binding energies (BEs; standard deviation =  $\pm$  0.2 eV) were corrected for charging effects by assigning to the adventitious C1s line a position of 284.8 eV. The root-mean-square (rms) uncertainty on each concentration value was assumed to be 15%, according to previous literature reports.<sup>36</sup>

Plane-view and cross-sectional FE-SEM images were recorded by a Zeiss SUPRA 40VP, using accelerating voltages between 10 and 20 kV.

AFM characterization was carried out by using a Nanoscope IIIa AFM (Digital Instruments) operated in contact mode, employing SiN cantilevers (Veeco) with a spring constant of 0.73 N m<sup>-1</sup>. rms roughness values were calculated from the height profile of  $2 \times 2 \mu m^2$  micrographs.

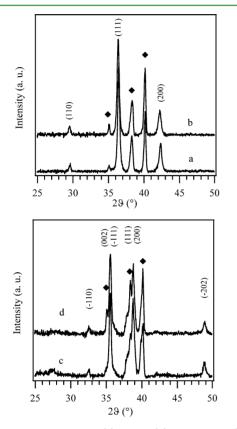
SIMS measurements were carried out by means of a IMS 4f mass spectrometer (Cameca), using a Cs<sup>+</sup> primary beam (14.5 keV, 12 nA) and negative secondary ion detection. The charge build up upon profiling was compensated by an electron gun. The signals were recorded in beam blanking mode in order to improve the in-depth resolution. Analyses were performed on 5 different sample regions in order to check the system homogeneity. The erosion speed was evaluated at the end of each analysis by measuring the crater depth through a Tencor Alpha Step profilometer (resolution close to 1 nm), and deposit thickness values were thus obtained. To avoid mass interference artifacts, measurements were performed in high mass resolution configuration. Data in Figure 3 have been plotted without taking into account the sputtering yield dependence on the local composition.

**Electrochemical Measurements.** Electrochemical tests were performed in two electrode Swagelok-type cells, using lithium as a counter electrode and a Merck battery electrolyte LP 40 [ethylene carbonate (EC) - diethyl carbonate (DEC), EC/DEC = 1:1 w/w, 1 M LiPF<sub>6</sub>]. Titanium pieces coated with the active nanomaterials were used as working electrodes. The oxide amount on each sample was determined by weighing the Ti substrate before and after deposition on a Sartorius microbalance (sensitivity =  $\pm 1 \mu$ g). For the Faradic yield calculation, the TiO<sub>2</sub> amount was considered negligible. Cells were galvanostatically charged and discharged at different cycling rates, from 0.1 to 2 C (C was defined as 375 and 674 mA h g<sup>-1</sup> for Cu<sub>2</sub>O and CuO samples, respectively). The electrodes were first discharged and, subsequently, maintained at their open circuit voltage in order to analyze the electrochemical impedance. After this procedure, the first charge curve started at potentials higher than 1.0 V. Measurements were controlled via a MacPile potentiostat-galvanostat.

Electrochemical impedance spectroscopy (EIS) analyses (frequency range =  $1 \times 10^{-5}$  to 90 kHz, amplitude = 3 mV) were performed by means of a Solartron 1470 battery test unit coupled to a Schlumberger SI 1255 response analyzer, on the same electrode at different stages during the cycling test.

## RESULTS AND DISCUSSION

**Chemical and Physical Characterization.** GIXRD patterns of  $Cu_xO$ -TiO<sub>2</sub> composites, together with those of the corresponding bare  $Cu_xO$  systems, are displayed in Figure 1. For  $Cu_2O$ -TiO<sub>2</sub>, only signals related to the  $Cu_2O$  crystalline



**Figure 1.** GIXRD patterns of: (a)  $Cu_2O$ , (b)  $Cu_2O$ -TiO<sub>2</sub>, (c) CuO, (d) CuO-TiO<sub>2</sub> samples. Peaks located at  $2\theta = 35.1$ , 38.4, and  $40.2^{\circ}$  ( $\blacklozenge$ ) are due to the titanium substrate.

phase (cuprite) could be observed ( $2\theta = 29.6$ , 36.4, and  $42.3^{\circ}$ ).<sup>37</sup> In the case of CuO-TiO<sub>2</sub>, GIXRD patterns were dominated by CuO (tenorite) reflections ( $2\theta = 32.5$ , 35.5, 38.7, and  $48.8^{\circ}$ ).<sup>38</sup> Regardless of the preparation conditions, no peaks corresponding to crystalline TiO<sub>2</sub> or to Cu–Ti–O ternary phases were present because of the high titania dispersion and moderate amount.<sup>32</sup> These observations highlighted the selective obtainment of Cu<sub>2</sub>O- and CuO-based materials by a proper choice of the substrate temperature (400 and 550 °C) and of the total operating pressure (3.0 and 10.0 mbar). For both copper oxide phases, the average crystallite size was estimated to be 30 ± 5 nm, regardless of TiO<sub>2</sub> presence.

To attain a deeper insight into the chemical composition, the nanosystems were characterized by XPS surface analysis (see Figure 2). The mean  $Ti2p_{3/2}$  BE (458.6 eV, Figure 2) pointed out to the formation of pure  $TiO_2$ ,<sup>29,31,32,39–41</sup> excluding the presence of Ti(III) and of any Cu–Ti–O ternary phase. As a

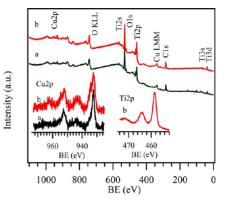


Figure 2. XPS surface survey, along with Cu2p and Ti2p signals, for: (a)  $Cu_2O$ -TiO<sub>2</sub>, and (b) CuO-TiO<sub>2</sub> nanocomposites.

general rule, copper signals could be observed even after  $\text{TiO}_2$  deposition because of the moderate titania content and its dispersion into the underlying matrix (see also SIMS depth profiles, Figure 3). In fact, the process did not produce a complete coverage of the underlying copper oxide matrices under the adopted conditions.

In particular, XPS surface mapping provided the following Cu:Ti atomic percentage ratios (at. %): 18.1:81.9 for Cu<sub>2</sub>O-TiO<sub>2</sub>, 16.7:83.3 for CuO-TiO<sub>2</sub>. In the case of Cu<sub>2</sub>O, the presence of Cu(I) was confirmed by the Cu2p<sub>3/2</sub> peak position (BE = 932.3 eV) and the absence of shake-up satellites.<sup>2,29,39–41</sup>

After TiO<sub>2</sub> deposition, no significant Cu2p spectral change took place, suggesting that the chemical nature of the Cu<sub>2</sub>O matrix remained almost unaltered. Regarding CuO specimen, the Cu2p<sub>3/2</sub> BE (934.0 eV), and the presence of shake-up satellites located at BE  $\approx$  9.0 eV higher than the related spinorbit components clearly indicated the occurrence of Cu(II).<sup>4,31,32,41</sup> The subsequent TiO<sub>2</sub> deposition resulted in a partial surface reduction of Cu(II) to Cu(I), as confirmed by: (i) the intensity decrease of shake-up peaks; (ii) the appearance of a Cu2p<sub>3/2</sub> band at 932.1 eV [assigned to Cu(II)], along with a shoulder located at 934.0 eV [assigned to Cu(II)]. The coexistence of Cu(I)-Cu(II) at the surface could be due to the presence of O-deficient titania particles acting as oxygen getters at the interface with CuO, as already reported.<sup>32,39</sup>

The in-depth penetration of TiO<sub>2</sub> into Cu<sub>x</sub>O matrices was investigated by SIMS, and representative profiles are displayed in Figure 3. All specimens presented a homogeneous composition, without any significant carbon contamination, and TiO<sub>2</sub> deposition over Cu<sub>x</sub>O matrices resulted in an increase of the overall deposit thickness (Table 1). Notably, an appreciable Cu<sub>x</sub>O-TiO<sub>2</sub> intermixing was detected, a phenomenon more evident in the case of CuO-based composites for the synergy between CuO roughness/porosity (see below) and the typical infiltration power of CVD techniques. Such characteristics were responsible for the tailing of copper signals into the substrates themselves. In fact, as can be observed from panels c and d in Figure 3, the deposit-Ti interface was significantly broadened for CuO-based systems. The maximumlike behavior in the Ti profile at the interface with the substrate, particularly evident in the case of Figure 3a, was due to the SIMS yield dependence on the sputtering yield coefficient, which in turn is a function of the matrix composition. This dependence implies that the same element (e.g., Ti) can have different yields upon passing from the target material to the substrate.

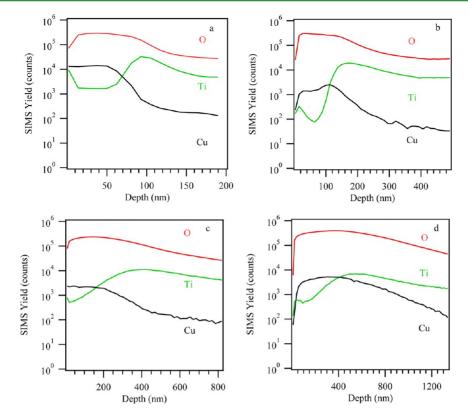


Figure 3. Representative SIMS depth profiles for: (a) Cu<sub>2</sub>O<sub>2</sub> (b) Cu<sub>2</sub>O-TiO<sub>2</sub>, (c) CuO, (d) CuO-TiO<sub>2</sub> nanocomposites.

Table 1. RMS Surface Roughness and Nanodeposit Thickness for Cu<sub>x</sub>O-TiO<sub>2</sub> Nanocomposites

rms roughness (nm)	thickness (nm)	sample
$30 \pm 2$	85 ± 15	Cu <sub>2</sub> O
$30 \pm 2$	$134 \pm 20$	Cu <sub>2</sub> O-TiO <sub>2</sub>
$70 \pm 3$	$275 \pm 55$	CuO
$140 \pm 5$	$325 \pm 85$	CuO-TiO <sub>2</sub>

FE-SEM and AFM micrographs (Figure 4) revealed that the different synthesis conditions used for Cu<sub>2</sub>O and CuO depositions had a significant influence even on the system nanoscale organization. For the thinnest Cu<sub>2</sub>O-based specimens, the morphology was mainly dominated by the typical corrugation of Ti substrate. In fact, as can be observed, a uniform conformal coverage of the latter by rounded Cu<sub>2</sub>O nanoaggregates (mean dimensions =  $100 \pm 20$  nm) took place, suggesting an isotropic growth mode. The subsequent TiO<sub>2</sub> deposition induced a mean nanoaggregate size increase of 30 nm, due to the deposition of TiO<sub>2</sub> particles on Cu<sub>2</sub>O grains (see Figure S1 in the Supporting Information). Conversely, the morphology of CuO-based nanosystems was characterized by the presence of interwoven aggregates, resulting in a highly porous deposit. The observed features had mean lateral sizes of  $450 \pm 50$  nm and were formed by the agglomeration of smaller grains (150  $\pm$  30 nm). Such values were higher than the crystallite sizes calculated by GIXRD data, suggesting that the observed particles were formed by the aggregation of various crystalline domains. Even in this case, titania deposition did not appreciably alter the pristine morphology of the bare CuO matrix, but induced only a mean increase of the lateral dimensions (200 and 50 nm for the above-mentioned interwoven aggregates and grains, respectively). Overall, these observations underlined the occurrence of a high TiO<sub>2</sub>

dispersion into the CuO matrix, with an intimate contact between the two oxides.

The surface rms roughness values obtained by AFM analyses are reported in Table 1. Note that after titania dispersion, no change occurred in the rms roughness values for Cu<sub>2</sub>O-based systems, highlighting a conformal coverage of the copper(I) oxide matrix. Conversely, CuO samples were appreciably rougher, and their coverage by TiO<sub>2</sub> resulted in a significant roughness increase. In the case of such systems, the high rms roughness was responsible for the appearance of flat-wall aggregates in AFM images, since these were not properly accessible to the AFM tip (see Figure 4c, d). The higher rms roughness values for CuO-based systems were indicative of a larger active area,<sup>8</sup> anticipating thus appreciable differences in the electrochemical behavior of Cu<sub>2</sub>O- and CuO-based nanocomposites.

**Electrochemical Characterization.** To test the applicability of the present systems as anodes in thin film batteries, their properties with respect to Li insertion/extraction were investigated. The galvanostatic charge/discharge curves recorded during the first three cycles for Li/Cu<sub>x</sub>O and Li/Cu<sub>x</sub>O-TiO<sub>2</sub> cells are displayed in Figure 5. The voltage profiles are similar to those already described for Cu<sub>2</sub>O<sup>25</sup> and CuO<sup>12,22,42</sup> electrodes and consistent with the following half-reactions<sup>1,2,43</sup>

$$Cu_2O + 2Li^+ + 2e^- \rightleftharpoons 2Cu + Li_2O \tag{2}$$

$$CuO + 2Li^{+} + 2e^{-} \rightleftharpoons Cu + Li_{2}O$$
(3)

Upon discharging,  $Cu_xO$  were transformed into nanometric Cu particles. After the first discharge cycle, the electrode Faradic yield exceeded the stoichiometric value for two electrons, a phenomenon which could be related to the formation of a solid electrolyte interphase (SEI) layer.<sup>8,44,45</sup> The presence of the

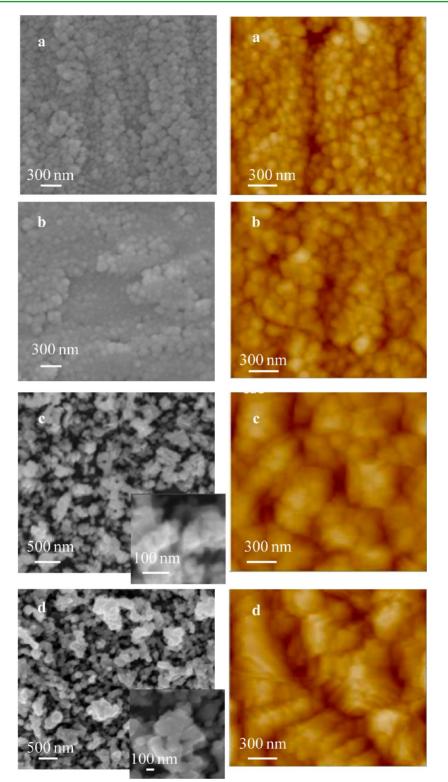


Figure 4. FE-SEM and AFM micrographs of: (a) Cu<sub>2</sub>O, (b) Cu<sub>2</sub>O-TiO<sub>2</sub>, (c) CuO, (d) CuO-TiO<sub>2</sub>.

latter was ascribed to the catalytic activity of metal particles, which can activate solvent molecules facilitating the charge transfer needed for redox processes.<sup>45</sup> Such a phenomenon explains why approximately twice the reversible capacity calculated for the samples was obtained at 0.1 C rate (compare Figure 6 and comments below). Notably, regardless of copper oxide nature, the dispersion of  $TiO_2$  increased the capacity delivered by the electrodes.

As a matter of fact, the exceeding Faradic yield value measured for each electrode was directly correlated with its microstructure and morphology, since electrodes exhibiting a larger interfacial area with the electrolyte facilitated its reduction and the SEI layer formation.<sup>4</sup> This phenomenon was more evident for CuO and TiO<sub>2</sub>-covered electrodes because of the synergistic contribution of the following factors: (i) CuO deposits were very porous and characterized by higher

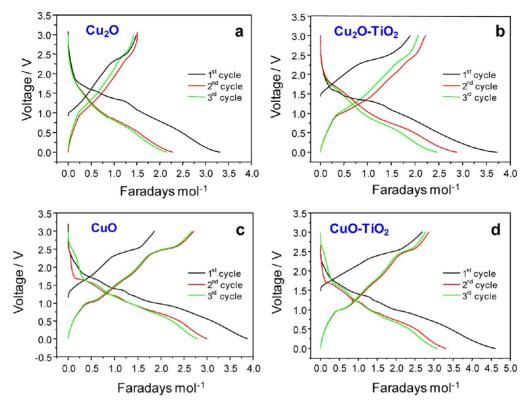


Figure 5. Charge/discharge voltage profiles during the first three operational cycles for: (a)  $Cu_2O$ , (b)  $Cu_2O$ -TiO<sub>2</sub>, (c) CuO, (d) CuO-TiO<sub>2</sub> specimens, cycled between 3.0 and 0.0 V (vs. Li<sup>+</sup>/Li).

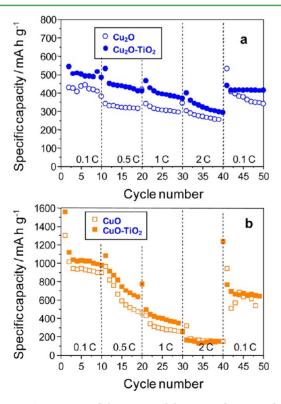


Figure 6. Comparison of the rate capabilities as a function of cycle number for the different nanocomposite electrodes. Voltage limits are between 3.0 and 0.0 V (vs.  $Li^+/Li$ ).

rms values than the more compact  $Cu_2O$  ones (compare Figure 3 and Table 1); (ii) the coverage of  $Cu_xO$  nanoaggregates by TiO<sub>2</sub> produced an increase of their mean size and/or roughness

(Table 1). The electricity amount involved in the first discharge was only partially extracted in the subsequent charging process, suggesting thus the occurrence of an incomplete  $\text{Li}_2\text{O/SEI}$  decomposition.<sup>8</sup> Nevertheless, under the 0.1 C regime, the SEI layer formation progressed and further proceeded during the following cycles, particularly for the CuO-based electrode. As a general trend, the charge/discharge curve shapes were rather similar upon cycling, indicating the occurrence of highly reversible electrochemical processes. No discernible signal was observed at 1.74 V, the voltage value attributed to lithiation/ delithiation of TiO<sub>2</sub>,<sup>46</sup> in agreement with the moderate content of this oxide.

The specific capacities of the different electrodes cycled in the 3.0-0.0 V range under various C regimes (see the Experimental Section) are reported in Figure 6. At 0.1 C, the delivered values for Cu<sub>2</sub>O and CuO samples were larger than the expected theoretical ones (375 and 674 mA h  $g^{-1}$ , respectively),<sup>2–4</sup> indicating the electrolyte participation to the cycling process,<sup>8</sup> as also supported by ex situ FE-SEM observations (Figure 8b). This phenomenon was more important at low C regimes (0.1 C), altering the observed cycle stability. The capacity evolution upon increasing the charging/discharging rate from 0.1 to 2 C was significantly influenced by the electrode microstructure and morphology. As a matter of fact, CuO and CuO-TiO<sub>2</sub> samples, constituted by bigger nanoaggregates forming thicker and highly porous deposits (see rms roughness values in Table 1), exhibited limited capacity retention upon faster cycling. Conversely, the more compact and thinner Cu<sub>2</sub>O and Cu<sub>2</sub>O-TiO<sub>2</sub> deposits possessed good cycling electrochemical performances and a maximum capacity loss of 35% was observed in the fastest regime (2 C). High capacity values were recovered when  $Cu_2O$ based electrodes were charged/discharged again at 0.1 C after

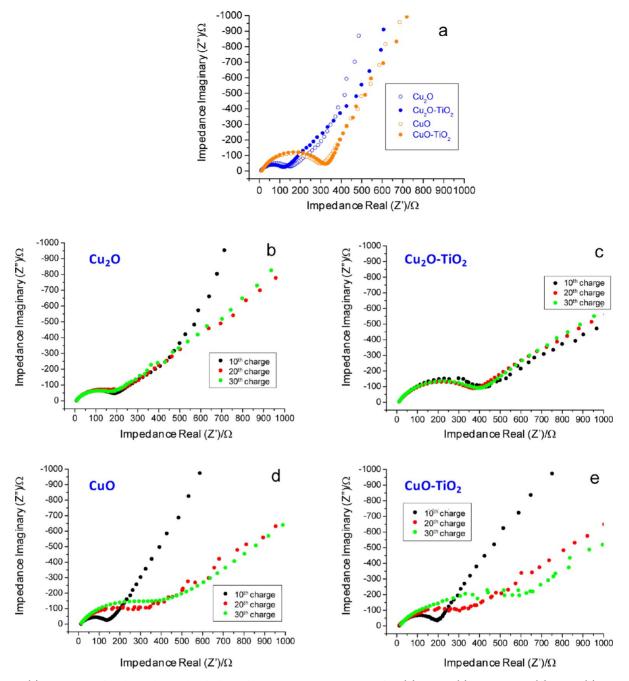


Figure 7. (a) EIS spectra for electrodes in the discharged state at 0.0 V. EIS spectra for: (b)  $Cu_2O$ , (c)  $Cu_2O$ -TiO<sub>2</sub>, (d) CuO, (e) CuO-TiO<sub>2</sub> electrodes in the charged state at 3.0 V, after various cycles.

40 cycles, reaching 80% of the original values. For  $Cu_2O-TiO_2$  systems (Figure 6a), upon returning to the 0.1 C regime after 40 cycles, an improved cycle stability with respect to the first 10 cycles was observed. This effect was traced back to a decreased electrolyte participation to the electrochemical process. Consistently, after 40 cycles, the delivered capacity (~400 mA h g<sup>-1</sup>) could be mainly ascribed to the reversible  $Cu_2O \rightleftharpoons$  Cu reaction, in agreement with the observed cycle stability.

The deposition of  $TiO_2$  had minor influence on the sample rate capability. For instance,  $Cu_2O$  samples retained 95 and 90% of the initial capacity when the operating regime was changed from 0.5 to 2 C (average capacity values: 320, 305, and 272 mA h g<sup>-1</sup> at 0.5, 1, and 2 C, respectively). In a different way, for  $Cu_2O$ -TiO<sub>2</sub> sample the corresponding capacity retention was lower, 91 and 81% (436, 396, and 324 mA h  $g^{-1}$  at 0.5, 1, and 2 C, respectively). The worse rate capability of TiO<sub>2</sub>-containing samples is in line with their larger impedance, as indicated by EIS analysis (see Figure 7 and related comments). It is also worth mentioning that all electrodes maintained values close to their theoretical capacity after cycling experiments.

To the best of our knowledge, the capacity values measured for both  $Cu_xO$ -TiO<sub>2</sub> systems are among the best ever reported to date for  $Cu_2O$  and CuO (see Table S1 in the Supporting Information), <sup>3,5,11,15,16,18,22,47</sup> demonstrating the technological potential of the adopted synthesis procedure. The worse electrochemical behavior of CuO-based electrodes could be explained on the basis of their morphology and thickness. As already discussed, their porosity, resulting in a higher interfacial area with the electrolyte than for Cu<sub>2</sub>O-based systems, facilitated the formation of a SEI polymeric film embedding CuO-containing particles, restricting, in turn, Li<sup>+</sup> diffusion through the active material. In addition, the electrochemical performances of copper oxide films were strongly dependent on thickness, indicating that the electron transfer from the Ti substrate through the whole nanodeposit directly influenced the electrochemical process kinetics.<sup>48</sup> Thus, during the charging process, when the metallic substrate acted as electron drain, the inner deposit layers were the first ones undergoing oxidation and the subsequent electron conduction from the outermost region was limited by the Cu  $\rightarrow$  Cu<sub>x</sub>O conversion. This effect was more pronounced for thicker systems, i.e., in the case of CuO-based nanocomposites.

To gain a better understanding of the system electrochemical behavior, a combined FE-SEM and EIS characterization was undertaken on the discharged electrodes. Figure 7a displays EIS spectra after the first discharge at 0.0 V. For all measurements, the Nyquist plots showed the characteristic depressed semicircle in the high- and middle-frequency range, followed by a straight line in the middle- to low-frequency range. As previously reported for Cu<sub>2</sub>O and CuO electrodes,<sup>5,11</sup> only one semicircle was observed, which is considered to arise from the superimposition of two separate contributions at high and medium frequencies. Whereas the former could be attributed to a polymerlike SEI film and/or contact resistance, the latter was related to Li<sup>+</sup> charge transfer impedance at the electrode/ electrody interface.<sup>8</sup>

At 0.0 V, both Cu<sub>2</sub>O-based electrodes show a smaller highmedium frequency semicircle than CuO-containing ones, indicating that both lithium ions and electrons could be transferred more easily across the Cu<sub>2</sub>O/electrolyte interface. This observation was in agreement with data of Figure 5, showing that the formation of a passive SEI film during the first discharge was favored for CuO-based systems. Upon cycling, impedance spectra were recorded at the end of the 10th, 20th and 30th charge process performed at 0.1, 0.5, and 1 C regimes, respectively. Even though the semicircle was extended to lower frequencies in the case of Cu<sub>2</sub>O and Cu<sub>2</sub>O-TiO<sub>2</sub> electrodes (Figure 7b, c), the Nyquist plot shapes did not significantly change, suggesting that both the electrode microstructure and the mobility of Li<sup>+</sup> and e<sup>-</sup> did not undergo significant variations during cycling. In a different way, in the case of CuO and CuO-TiO<sub>2</sub>, the semicircle became more extended upon increasing the cycle number (Figure 7d, e), indicating a progressive growth of the SEI film and explaining the inferior electrochemical performance of these electrodes under high charge/ discharge regimes.

For both Cu<sub>2</sub>O- and CuO-based systems, TiO<sub>2</sub> introduction resulted in an impedance increase with respect to the bare Cu<sub>x</sub>O matrices, that could be traced back to: (i) a favored electrolyte degradation and formation of SEI film;<sup>49</sup> (ii) a limited electron transfer, due to the poor titania electron conduction. On the other hand, it is worth noting that this phenomenon is not a handicap in order to achieve an optimal electrochemical behavior, as observed in the case of Cu<sub>2</sub>O-TiO<sub>2</sub>.

Figure 8 shows the FE-SEM images recorded after electrochemical tests, which revealed the occurrence of various changes with respect to the as-grown systems (Figure 4). For  $Cu_2O$  and  $Cu_2O$ -Ti $O_2$ , a compact morphology was present and the pristine nanoparticulate features could no more be

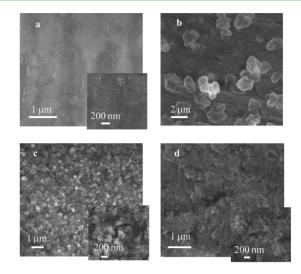


Figure 8. FE-SEM images of: (a)  $Cu_2O$ , (b)  $Cu_2O$ -TiO<sub>2</sub>, (c) CuO, (d) CuO-TiO<sub>2</sub> electrodes, recorded after the cycling tests.

discerned. The development of cracks on Cu<sub>2</sub>O (Figure 8a, inset), which could limit the electron conduction through the electrode, was induced by the volume variations experienced upon electrochemical cycling.<sup>4,6,8,15</sup> In addition, the Cu<sub>2</sub>O electrode was completely covered by a jelly film (Figure 8a). Significant alterations were observed for Cu<sub>2</sub>O-TiO<sub>2</sub> (Figure 8b), namely: (i) large aggregates appeared on the electrode surface, likely attributable to electrolyte degradation products; (ii) no jelly film could be observed (see also below); (iii) no cracks could be clearly detected. The fact that TiO<sub>2</sub> particles covered the Cu<sub>2</sub>O matrix, as inferred from XPS, SIMS and AFM data, evidenced titania role as buffer material, preserving the system structure upon cycling.<sup>50</sup> Conversely, CuO and CuO-TiO<sub>2</sub> exhibited similar aggregate sizes and their pristine porous topography appeared to be filled by a polymeric material (Figure 8c, d), further supporting the promotional effect of this peculiar morphology on the formation of the SEI layer, which worsened the system electrochemical performances.

The role of TiO<sub>2</sub> on the electrochemical performances of copper oxide electrodes can be explained in detail considering Cu<sub>2</sub>O-containing systems as an example. On the basis of SIMS results, TiO<sub>2</sub> was located not only in the outermost system region but also in the inner one. The surface presence of titania enhances the SEI film formation because of TiO<sub>2</sub> activity in the electrochemical electrolyte degradation,<sup>49</sup> resulting in the observed capacity excess upon discharging TiO<sub>2</sub>-containing electrodes. This behavior, together with the poor titania conductivity, precludes a fast transfer of both lithium ions and electrons through the copper oxide matrix, deteriorating the rate capability of Cu<sub>x</sub>O-TiO<sub>2</sub> electrodes.

This detrimental titania contribution is counterbalanced by its beneficial influence on the delivered electrode capacity, a phenomenon occurring irrespective of copper oxide nature, that can be traced back to the concurrence of two main causes. The first one is the buffering effect exerted by  $Cu_xO-TiO_2$ intermixing, lowering, in turn, volume changes occurring during reactions (2) and (3) with respect to the bare  $Cu_xO$  systems. Such an explanation is perfectly in line with observations on the lithium insertion/extraction process for ZnO nanorods functionalized with TiO<sub>2</sub> nanoparticles.<sup>50</sup> No cracks, whose formation would be a handicap for electron conduction, were observed on  $Cu_xO-TiO_2$  electrodes, in line with the good capacity retention observed after 40 cycles.

The second cause explaining the increased capacity for  $Cu_xO$ -TiO<sub>2</sub> systems is related to the dynamics of SEI layer formation/reoxidation, both being activated by TiO<sub>2</sub> presence. Indeed, as already reported, TiO<sub>2</sub> enhanced the electrochemical reactivity of Fe<sub>2</sub>O<sub>3</sub> anodes by promoting the electrolyte redox process.<sup>46</sup> In the present case, the two-fold TiO<sub>2</sub> role is supported by FE-SEM micrographs of panels a and in Figure 8, displaying significant differences between bare Cu<sub>2</sub>O and Cu<sub>2</sub>O-TiO<sub>2</sub> systems after electrochemical cycling. In fact, a jelly SEI film was observed on the surface of the bare Cu<sub>2</sub>O electrode, but not on the Cu<sub>2</sub>O-TiO<sub>2</sub> one.

#### CONCLUSIONS

In summary, we have proposed a successful vapor phase route to develop  $Cu_x O-TiO_2$  (x = 1, 2) nanoelectrodes free from ancillary additives. A suitable choice of the growth temperature and oxygen total pressure enabled the selective preparation of Cu<sub>2</sub>O/CuO matrices with tailored nano-organization, over which TiO<sub>2</sub> nanoparticles were subsequently dispersed. As a result, high-purity  $Cu_x O$ -TiO<sub>2</sub> (x = 1, 2) nanocomposites with an intimate contact between CurO and TiO2 were obtained. We also showed that the morphology and nano-organization of Cu<sub>x</sub>O-TiO<sub>2</sub> composites had a significant influence on their electrochemical performances as anodes in thin film lithium batteries, resulting in Coulombic efficiencies and rate capabilities among the highest ever reported for Cu<sub>r</sub>O-based materials. In the case of CuO-TiO<sub>2</sub>, the porous structure promoted the formation of a SEI polymeric film, restricting thus Li<sup>+</sup> diffusion through the active material, while the high deposit thickness constrained the electron transfer. Both effects were responsible for the limited capacity retention at fast regimes. In a different way, as regards Cu<sub>2</sub>O-TiO<sub>2</sub> electrodes, enhanced cycling performances were obtained. In this case, the introduction of TiO<sub>2</sub> minimizes the formation of cracks on the electrode surface and promotes the electrochemical redox conversion of the SEI layer.

Overall, these results give clear evidence of the attractive material performances as thin film battery anodes. The most interesting future perspectives for advancements of the present activities will concern the functional validation of  $Cu_xO-TiO_2$  systems after more prolonged electrochemical cycling, an important issue in view of practical technological applications. In addition, the applicability of the present strategy to other nanocomposite oxides will also be investigated, in order to further explore its potential for the development of thin film Li batteries with outstanding efficiency.

### ASSOCIATED CONTENT

#### **S** Supporting Information

Additional figure and table (PDF). This material is available free of charge via the Internet at http://pubs.acs.org.

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#### Notes

The authors declare no competing financial interest.

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